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PATENT NUMBER and  
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10083163	FILING DATE 02/27/2002	CLASS 207 438	SUBCLASS 377	GAV 2826 2812	EXAMINER Dickey
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\*\*APPLICANTS: Hokazono Akira; TB

\*\*CONTINUING DATA VERIFIED:

None TB

\*\* FOREIGN APPLICATIONS VERIFIED:

JAPAN 2001-392559 12/25/2001 TB

PG-PUE	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>
Foreign priority claimed 35 USC 119 conditions met		<input checked="" type="checkbox"/> Yes <input type="checkbox"/> No <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No
ATTORNEY DOCKET NO Verified and Acknowledged Examiners's initials TB 220110US2S		
TITLE : Semiconductor device having active regions connected together by interconnect layer and method of manufacture thereof		

U.S.DEPT. OF COMM./PAT & TM-PTO-436L(Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		Assistant Examiner	CLAIMS ALLOWED	
			Total Claims	Print Claim for O.G
ISSUE FEE		DRAWING		
Amount Due	Date Paid	Sheets Drwg.	Figs.Drwg.	Print Fig.
<input type="checkbox"/> TERMINAL DISCLAIMER		Primary Examiner		
		PREPARED FOR ISSUE		
		Application Examiner		
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